

Greetings from Japan!

The 12th International Conference on Radiation Curing in Asia (RadTech Asia 2009) will be held in Yokohama, Japan during November 24-27, 2009. On behalf of the RadTech Asia 2009 Organizing Committee, Prof. Tadatomi Nishikubo, the chair of the Organizing Committee cordially invites you to participate in the conference.

The RadTech Asia 2009 will focus on the current market trend of UV/EB processing at home and abroad and on its technical issues, and will have an opportunity to exchange information to create new seeds of the future science, technology and industry. It will also include discussions on various topics such as the development of recyclable and biodegradable materials, energy-saving processes, and high-performance exposure equipment as environment-friendly technologies, measurement devices, and technologies as the basis of the nanotech industry and high-efficiency nano-materials.

RadTech Asia 2009 Exhibition will provide good opportunities to see new materials and equipments. Scientists, engineers and users worldwide are all welcome to join us at RadTech Asia 2009. I am looking forward to meeting you in Yokohama.

Conference Dates

November 24th (Tue) - 27th (Fri), 2009

Conference Venue

Pacifico Yokohama
1-1-1, Minatomirai, Nishi-ku, Yokohama 220-0012, Japan
<http://www.pacifico.co.jp/english/>

Registration

Registration will start from 2 March, 2009.

Categories	Early Bird (Until September 30, 2009)	Late & On-site (From October 1, 2009)
Industries	JPY 80,000	JPY 90,000
Governments and Academia	JPY 40,000	JPY 50,000
Speakers form Industries	JPY 40,000	
Speakers form Governments and Academia	JPY 30,000	
Student*	JPY 10,000	
Accompanying Person**	JPY 10,000	

* Students are required to submit a copy of their student ID or a student certificate letter by the supervisor by fax to +81-3-3292-1811.

** Accompanying persons are limited to the participants' family members only.

Conference Program

Nov. 24 (Tue): AM/PM Technical Visit
EVE Get-Together
Nov. 25(Wed): AM Opening Ceremony / Area Overview
PM Session / Exhibition
EVE Poster Session
Nov. 26 (Thu) AM/PM Session / Exhibition
EVE Buffet Dinner
Nov. 27 (Fri) AM Session / Exhibition

The number of Plenary and Invited Lectures planned in the conference is available also in our website and 2nd circular.

The main theme of RadTech Asia 2009 is as follows;

- 1) Area Overviews
- 2) Special Sessions
 - S-1: Nano Imprint
 - S-2: Nano Lithography

- S-3: Green Technology
- S-4: New Trend in Display Technology

3) General Sessions:

- G-1 Equipment: UV/EB Systems, Laser Sources
- G-2 Chemistry: Monomers, Laser Sources, Pre Polymers, Additives, Reaction Mechanisms
- G-3 Performance Measurement / Testing: Dosimetry, Degree of Curing, Physical/Chemical Properties
- G-4: Applications:
 - G-4-1 Printings: Publishing, Packaging, Others
 - G-4-2 Coatings: Wood, Metals, Inorganic Materials, Plastics, Papers
 - G-4-3 Adhesives: Laminating, Pressure Sensitive, Release Coating
 - G-4-4 Photofabrications: 3D-Fabrication, Micro-and Nano Fabrications
 - G-4-5 Electronics: UV/EB and X-Ray Resists, Printed Circuits Boards, Lithographic Process.
 - G-4-6 Information Transfer and Recording: Optical Fibers, Magnetic Media, Optical Media
 - G-4-7 Biological and Medical
- G-5 Safety and Handling
- G-6 Emerging Technologies

Abstract Submission

The abstract submission page is available through our website; <http://www.radtechasia2009.org>, and the deadline for submission is on **Saturday, February 28th, 2009**.

Second Announcement

Second Announcement has been published. It is available through our website; <http://www.radtechasia2009.org/>

Exhibition Outline

Venue: 3F, Conference Center

Opening Hours: Nov.25 (Wed.) 9:00-17:00
Nov. 26 (Thu.) 9:00-17:00
Nov. 27 (Fri.) 9:00-15:00

Exhibition Fee:

Shell scheme booth: Width 1.98m x Depth 1.98m x Height 2.4m
1 booth 250,000 JPY
2 booths or more 200,000 JPY / per booth

Allotment:

Booths will be allocated on a first-come first-served basis. Please visit our website for floor plan and application form.

Conference Secretariat

Secretariat for RadTech Asia 2009
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<http://www.radtechasia2009.org/>